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(12) **United States Design Patent**  
**Podubni**

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(54) **MODULAR CIRCUIT BOARD**

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(73) Assignee: **TinyPCB, Inc.**

(\*\*) Term: **15 Years**

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(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**

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361/720, 728, 736, 748, 751, 752, 760,  
361/761, 807; 439/55, 65, 68, 76.1, 92,  
439/93, 95

CPC ..... H05K 3/00; H05K 3/30; H05K 3/301;  
H05K 3/303; H05K 3/34; H05K 3/3405;  
H05K 3/341; H05K 3/36; H05K 3/361;  
H05K 3/363; H05K 3/40; H05K 7/14;  
H05K 7/1422; H05K 7/00; H05K 1/18;  
H05K 1/02; H05K 1/181; H05K 1/182;  
H05K 1/183; H05K 1/184; H05K 1/189;  
H05K 1/00

See application file for complete search history.

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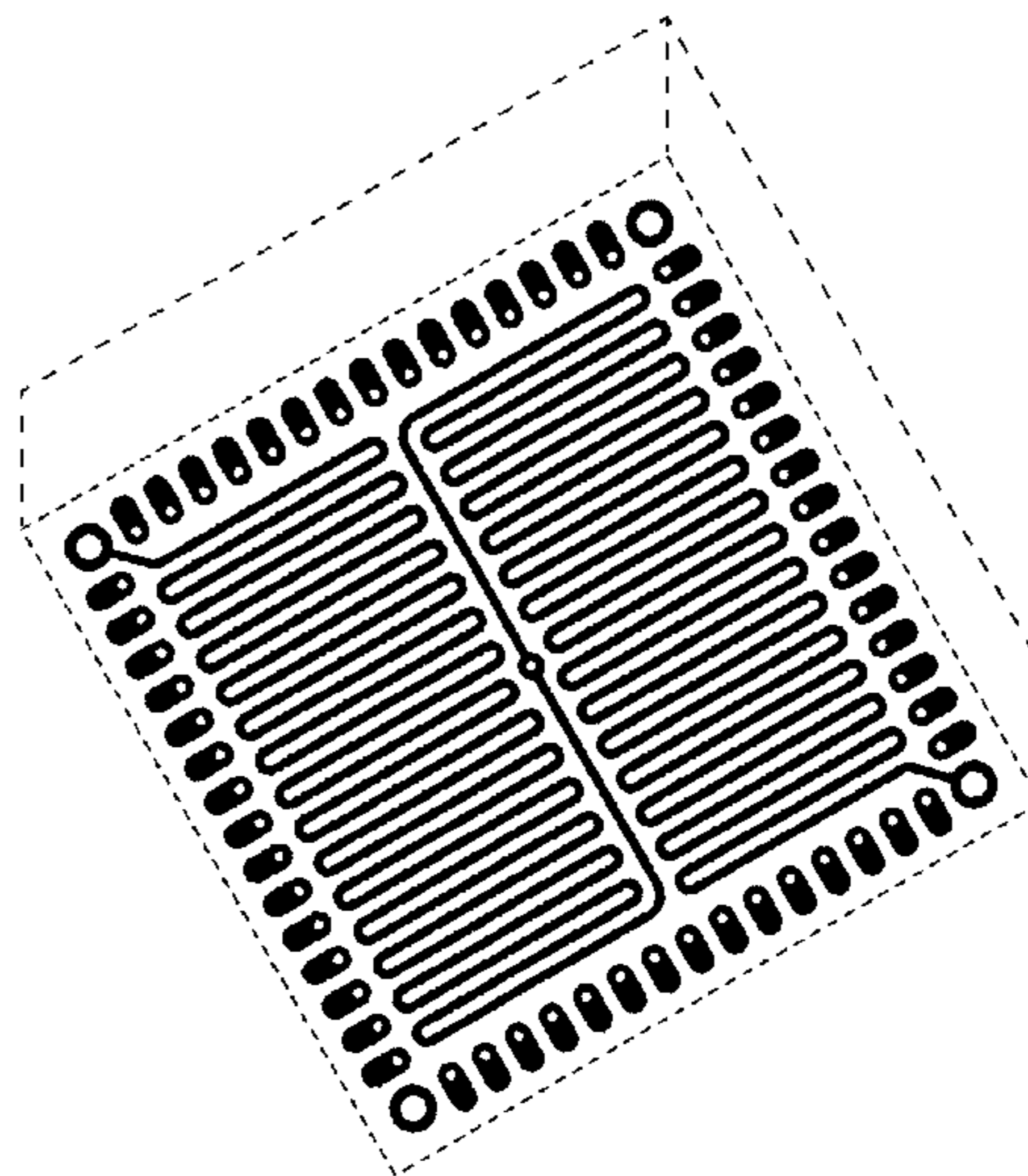
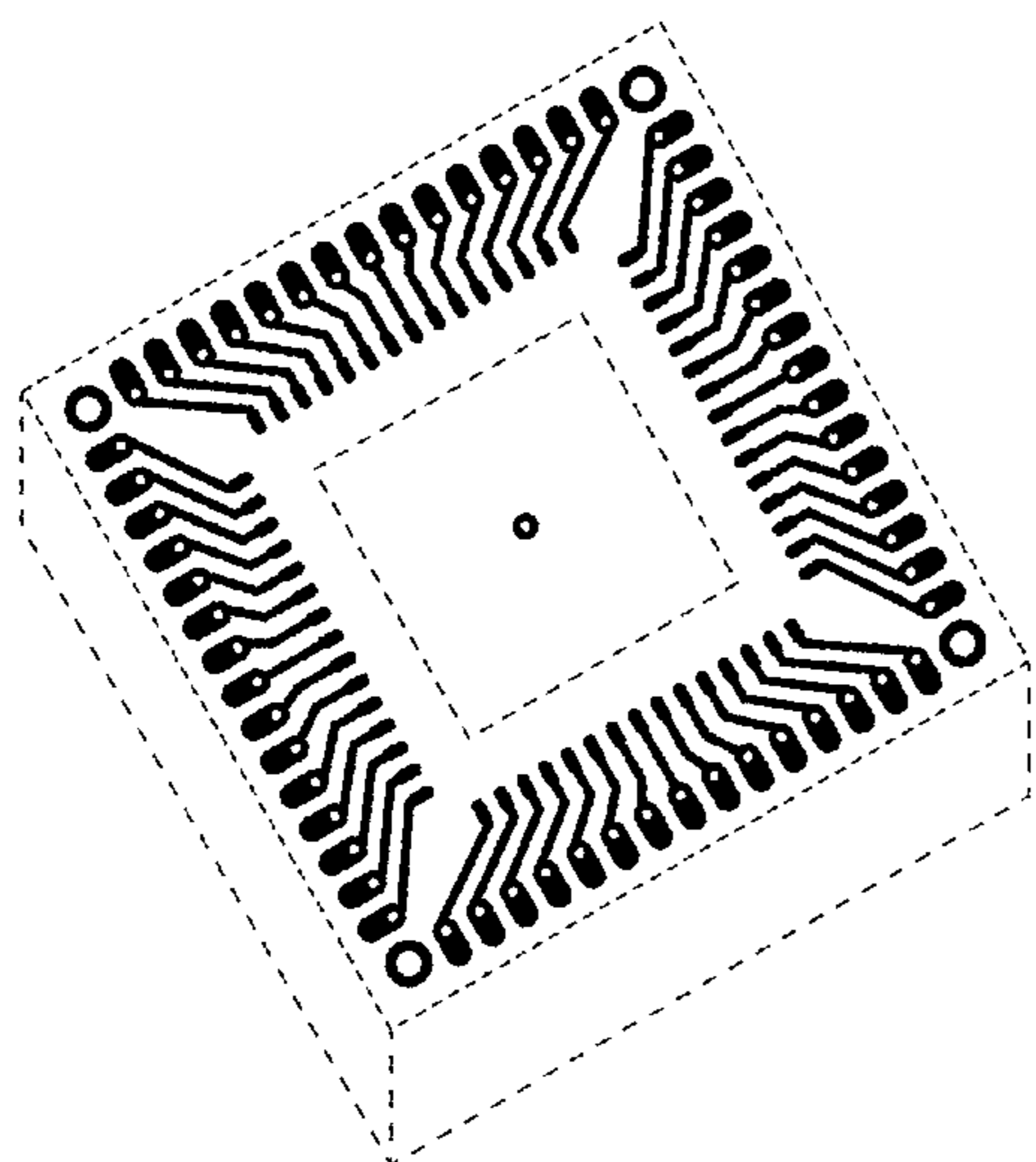
(57) **CLAIM**

The ornamental design for a modular circuit board, as shown and described.

**DESCRIPTION**

FIG. 1 is a top perspective view of a modular circuit board, showing my new design;  
 FIG. 2 is a bottom perspective view thereof;  
 FIG. 3 is a top view thereof;  
 FIG. 4 is a bottom view thereof; and,  
 FIG. 5 is a side view thereof, all other side views being a mirror image thereof.  
 The broken lines shown in the drawings represent portions of the modular circuit board that form no part of the claimed design.

**1 Claim, 5 Drawing Sheets**



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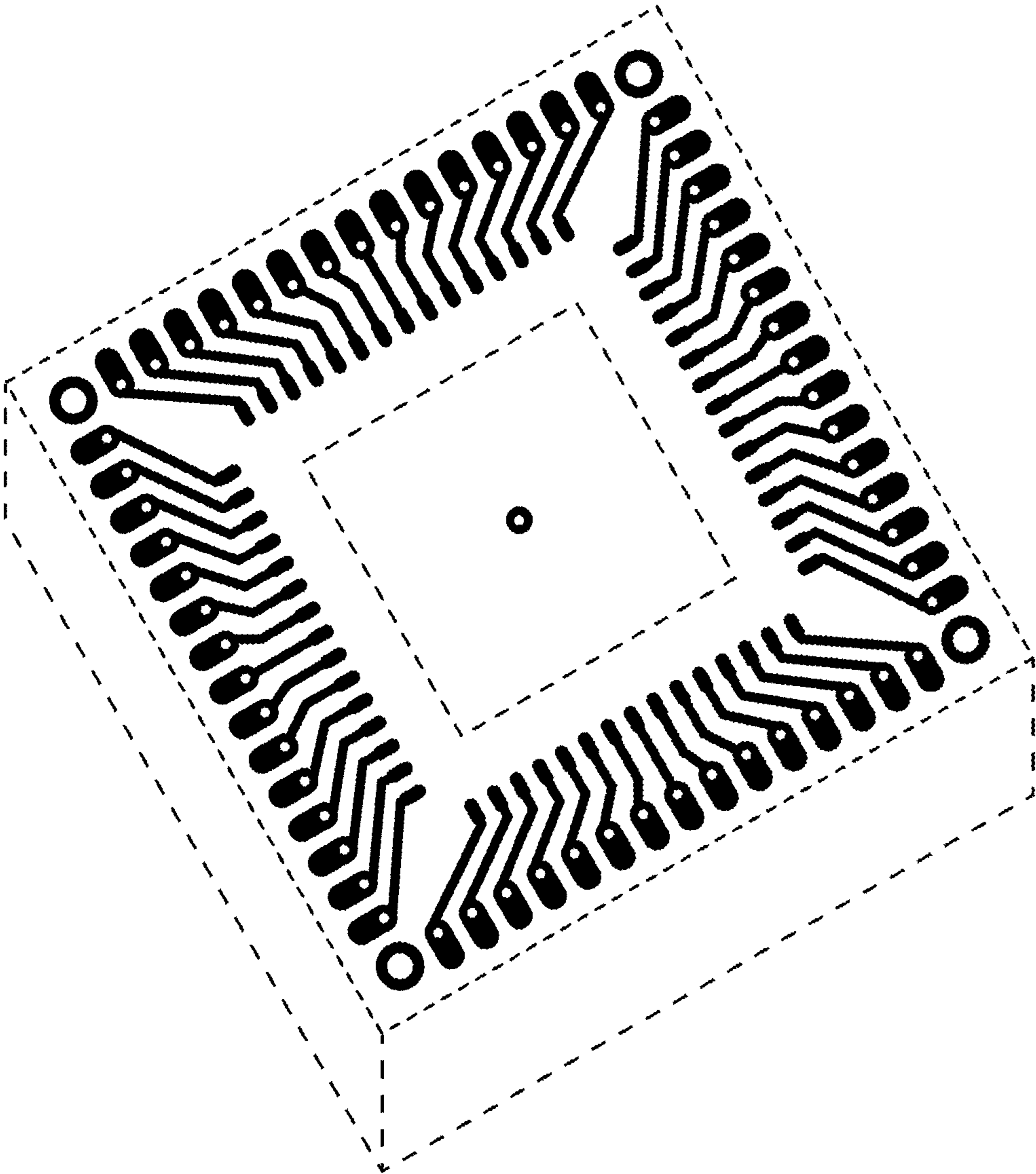


FIG. 1

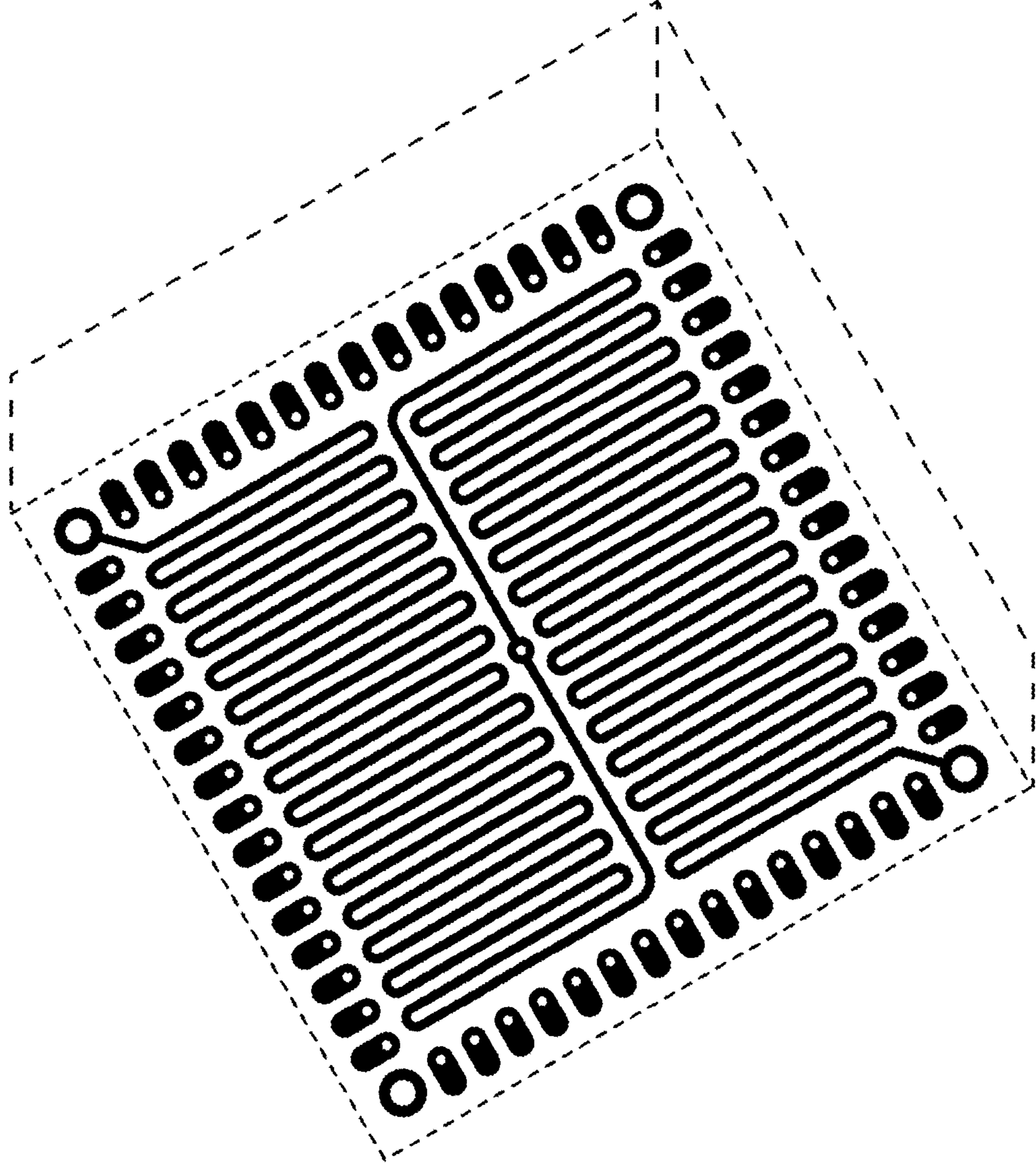


FIG. 2



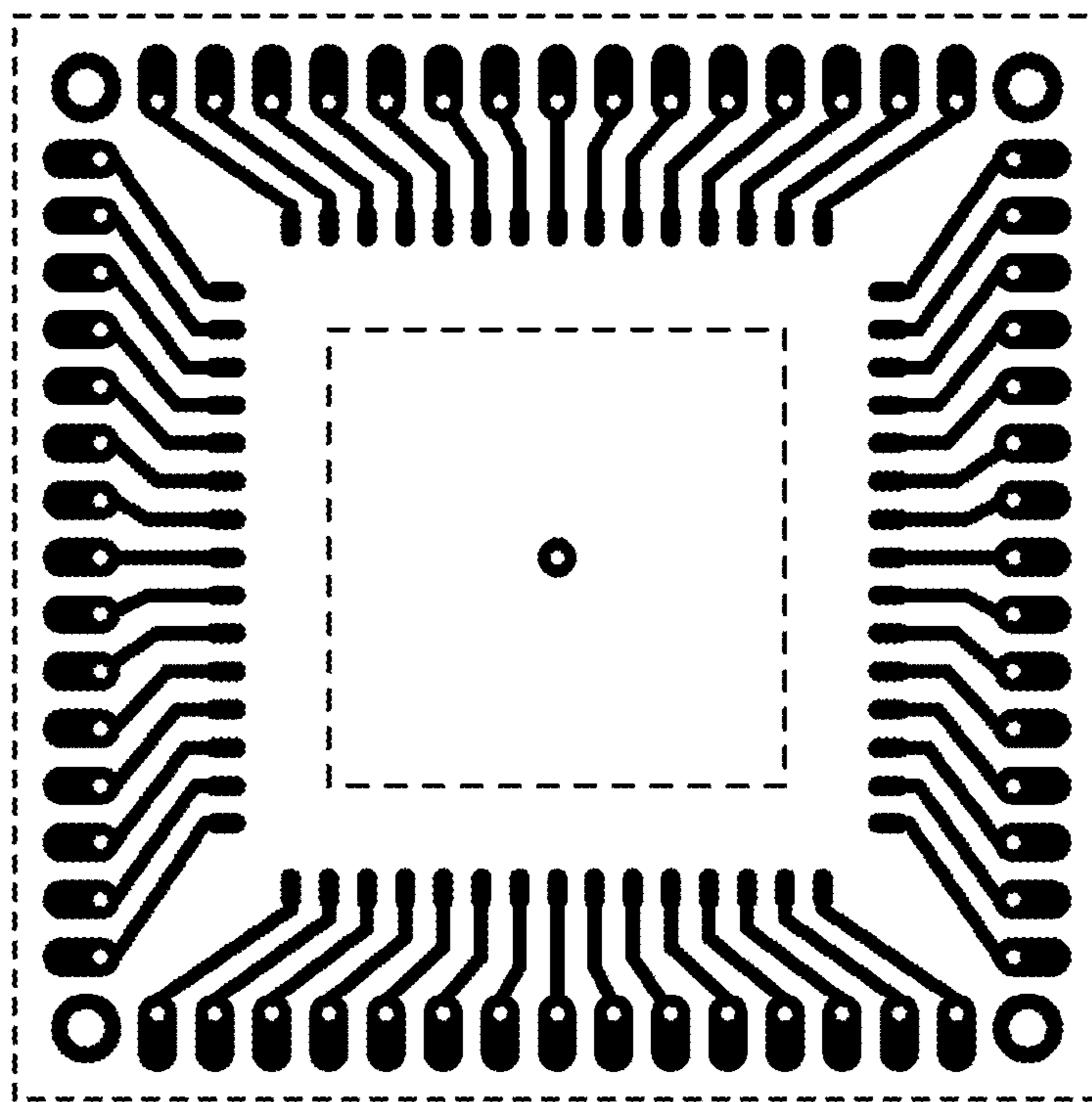


FIG. 3

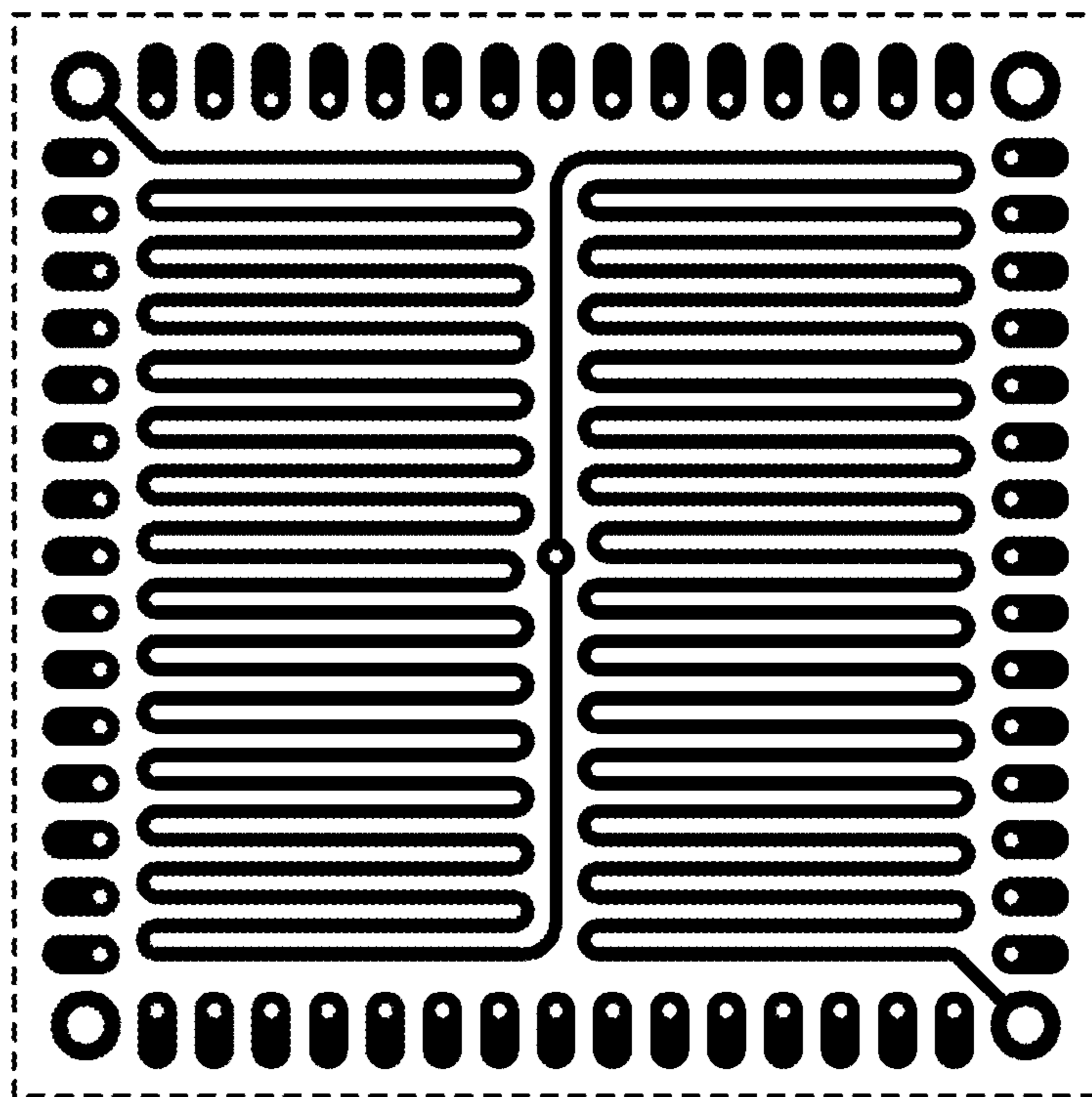


FIG. 4



FIG. 5